Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ( $L^2-\pi$ -MOSV)

## 2SK2200

# Chopper Regulator, DC-DC Converter and Motor Drive Applications

• 4 V gate drive

• Low drain—source ON resistance  $: R_{DS}(ON) = 0.28 \Omega \text{ (typ.)}$ • High forward transfer admittance  $: |Y_{fs}| = 3.5 \text{ S (typ.)}$ • Low leakage current  $: I_{DSS} = 100 \text{ } \mu\text{A (max)} \text{ (V}_{DS} = 100 \text{ V)}$ 

• Enhancement-mode :  $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

### **Maximum Ratings (Ta = 25°C)**

Characteri	stics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	100	V	
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		$V_{DGR}$	100	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	3	Α	
	Pulse (Note 1)	I <sub>DP</sub>	12	Α	
Drain power dissipation	n (Tc = 25°C)	P <sub>D</sub>	1.3	W	
Single pulse avalanch	e energy (Note 2)	E <sub>AS</sub>	140	mJ	
Avalanche current		I <sub>AR</sub>	3	Α	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	0.13	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

#### 8.0 ± 0.2 70 + 0.2 1.4 ± 0.1 1.05 ± 0.1 1.05 ± 0.1 2.5 ± 0.5 1.2 3 1.2 3 1.3 ± 0.1 1.4 ± 0.1 1.4 ± 0.1 1.4 ± 0.1 1.5 ± 0.1 1.5 ± 0.1 1.5 ± 0.5 1.5 ± 0.5 1.5 ± 0.5

2-8M1B

Weight: 0.54 g (typ.)

1.SOURCE 2.DRAIN 3.GATE

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#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	96.1	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = 50 V,  $T_{ch}$  = 25°C (initial), L = 25 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 3 A

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device.

Please handle with caution.

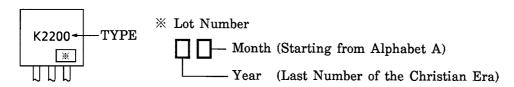
## Electrical Characteristics (Ta = 25°C)

Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Drain cut-off cur	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V	_	_	100	μΑ
Drain-source br voltage	eakdown	V <sub>(BR) DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	100	_	_	V
Gate threshold v	oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	0.8	_	2.0	V
Drain-source O	N rocietanco	Pro (OVI)	V <sub>GS</sub> = 4 V, I <sub>D</sub> = 2 A	_	0.36	0.45	mΩ
Dialii-Source Of	N resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2 A	_	0.28	0.35	
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 2 A	1.5	3.5	_	S
Input capacitano	e	C <sub>iss</sub>		_	280	_	
Reverse transfer	r capacitance	C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	50	_	pF
Output capacitance		C <sub>oss</sub>		_	105	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS} \stackrel{10 \text{ V}}{\text{O} \text{ V}} \stackrel{\text{I}_{D} = 2 \text{ A}}{\text{O} \text{ V}_{OUT}}$ $\stackrel{\text{C}}{\text{C}} \stackrel{\text{C}}{\text{C}} \stackrel{\text{C}} \stackrel{\text{C}}{\text{C}} \stackrel{\text{C}}{\text{C}} \stackrel{\text{C}}{\text{C}} \stackrel{\text{C}}{\text{C}} \text$	_	20	_	
	Turn-on time	t <sub>on</sub>		_	50	_	ns
	Fall time	t <sub>f</sub>		_	40	_	
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\rm W} = 10 \mu{\rm s}$	_	170	-	
Total gate charge (Gate-source plus gate-drain)		Qg			13.5		
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 80 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$		8.5	_	nC
Gate-drain ("miller") charge		Q <sub>gd</sub>		_	5	_	

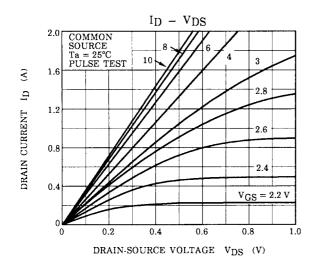
## **Source-Drain Ratings and Characteristics (Ta = 25°C)**

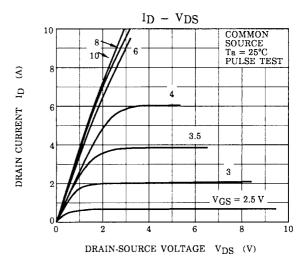
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	3	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	-	_	12	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 3 A, V <sub>GS</sub> = 0 V	_	_	-1.5	V
Reverse recovery time	t <sub>rr</sub>	$I_{DR} = 3 \text{ A}, V_{GS} = 0 \text{ V}, dI_{DR} / dt = 50 \text{ A} / \mu \text{s}$		100	_	ns
Reverse recovered charge	Q <sub>rr</sub>		_	0.2	_	μC

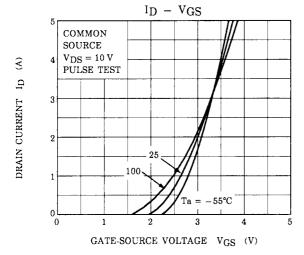
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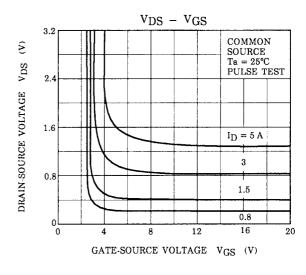


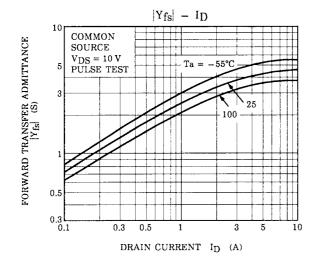
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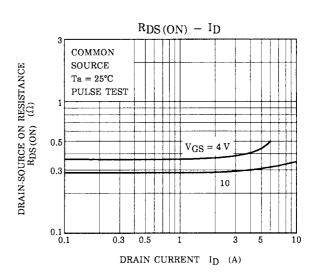




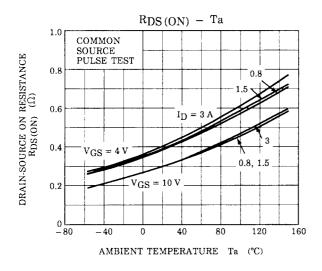


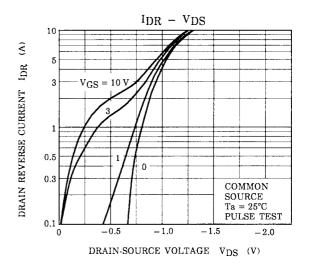


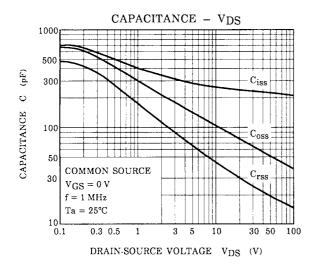


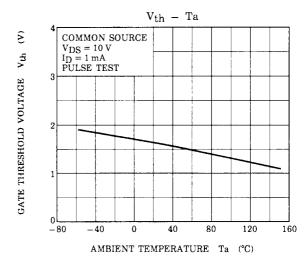


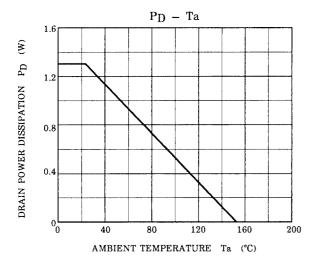
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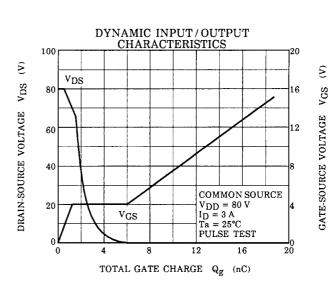




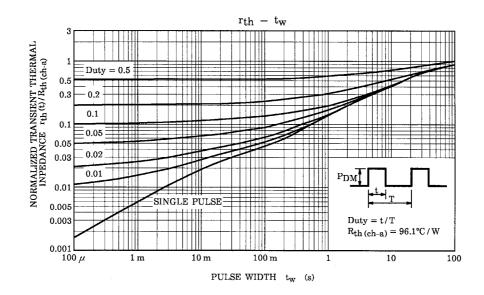


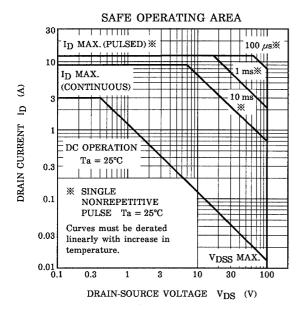


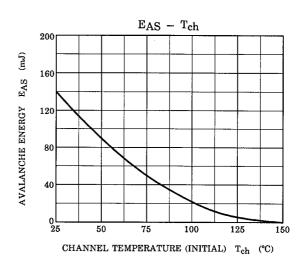


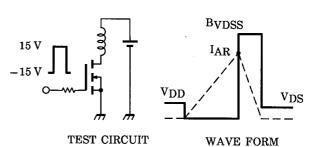


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$$\begin{aligned} R_G &= 25 \ \Omega \\ V_{DD} &= 25 \ V, \ L = 25 \ mH \end{aligned} \qquad EAS = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{BVDSS}{BVDSS - V_{DD}} \right)$$

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